



Material Content Data Sheet



Sales Product Name		TLE4270-2G		Issued		1. August 2018		
MA#		MA000714122						
Package		PG-TO263-5-1		Weight*		1675.01 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.930	0.29	0.29	2943	2943
leadframe	inorganic material	phosphorus	7723-14-0	0.145	0.01		86	
	non noble metal	iron	7439-89-6	0.483	0.03		288	
	non noble metal	copper	7440-50-8	482.096	28.78	28.82	287817	288191
	non noble metal	aluminium	7429-90-5	0.306	0.02	0.02	182	182
wire	non noble metal	aluminium	7429-90-5	0.306	0.02	0.02	182	182
encapsulation	organic material	carbon black	1333-86-4	1.453	0.09		867	
	plastics	epoxy resin	-	66.822	3.99		39894	
	inorganic material	silicondioxide	60676-86-0	658.055	39.27	43.35	392865	433626
leadfinish	non noble metal	tin	7440-31-5	12.370	0.74	0.74	7385	7385
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.243	0.01	0.01	145	146
solder	non noble metal	tin	7440-31-5	0.122	0.01		73	
	noble metal	silver	7440-22-4	0.152	0.01		91	
	non noble metal	lead	7439-92-1	5.806	0.35	0.37	3466	3630
heatspreader	inorganic material	phosphorus	7723-14-0	0.133	0.01		79	
	non noble metal	iron	7439-89-6	0.442	0.03		264	
	non noble metal	copper	7440-50-8	441.456	26.36	26.40	263554	263897
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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